TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

T6L09

SOURCE DRIVER FOR TFT LCD PANELS

The T6L09 is a 240-channel-output source driver for TFT LCD panels. Its sampling select pin allows switching of the VIDEO input signals (R, G, B) to the desired output pins. Furthermore, two or more of these devices can be used in combination enabling designers to keep pace with increasing LCD panel sizes.

The T6L09 offers both low power consumption and high integration circuit due to CMOS technology.

FEATURES

LCD drive output pins : 240 pins

(80 pins each for R, G and B)

LCD drive voltage : Max 15 V

Data transfer method : Bidirectional shift register

Operating temperature : -20 to 75°C

Package : Tape carrier package (TCP)

TFT LCD gate driver : T6L08

Unit: mm USER AREA T6L09 PITCH (SGN, 7ES) 1.0 0.09

Please contact Toshiba or a distributor for the latest TCP specification and product line-up.

TCP (Tape Carrier Package)

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Polyimide base film is hard and thin. Be careful not to injure yourself on the film or to scratch any other parts with the film. Try to design and manufacture products so that there is no chance of users touching the film after assembly, or if they do , that there is no chance of them injuring themselves. When cutting out the film, try to ensure that the film shavings do not cause accidents. After use, treat the leftover film and reel spacers as industrial waste.

Light striking a semiconductor device generates electromotive force due to photoelectric effects. In some cases this can

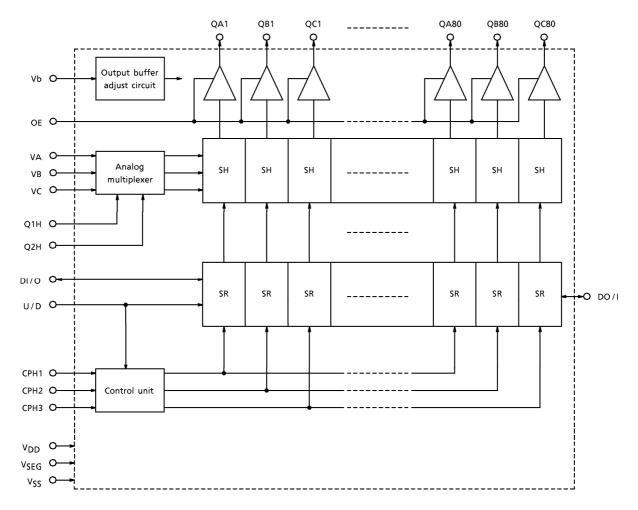
cause the device to malfunction. This is especially true for devices in which the surface (back), or side of the chip is exposed. When designing circuits, make sure that devices are protected against incident light from external sources. Exposure to light both during regular operation and during inspection must be taken into account.

The products described in this document are subject to the foreign exchange and foreign trade laws.

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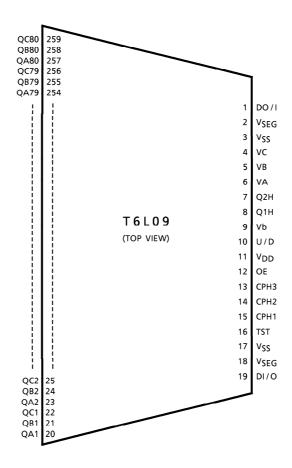
BLOCK DIAGRAM



SR : Shift Register

SH : Sample-and-Hold Circuit

PIN ASSIGNMENT



The above diagram shows the device's pin configuration only and does not necessarily correspond to the pad layout on the chip. Please contact Toshiba or our distributors for the latest TCP specification.

PIN FUNCTION

PIN NAME	1/0			FUNCTIO	N		
		Vertical shift data I/O pins These pins are used to input and output shift data. These pins are switched for input or output by setting the U/D pin as shown below.					
			U/D	DI/O	DO/I		
DI/O			H L	INPUT OUTPUT	OUTPUT INPUT		
DO / I	1/0	LCD driver. The o CPH1. When set for outpu	ata is latc t re T6L09s	hed into the s	hift registers	the first stage of the at the rising edge of uts the data to be fed	
U/D	Input	Transfer direction se This pin specifies hold circuit. When U/D is QA1→QB1→ When U/D is QC80→QB80→	When U/D is high, data is sampled in the sequence $QA1 \rightarrow QB1 \rightarrow QC1 \rightarrow QA2 \rightarrow QB2 \rightarrow \cdots \rightarrow QC80$ When U/D is low, the sequence is reversed to give $QC80 \rightarrow QB80 \rightarrow QA80 \rightarrow QC79 \rightarrow \cdots \rightarrow QA1$ The voltage applied to this pin must be a DC-level voltage that is either				
CPH1 to 3	Input	Shift clock input These clocks sequ					
OE	Input	Output enable input This signal enable The LCD drive ou					
Q1H/Q2H	Input	Analog signal select These signals swit output pins: QA,	ch the inp		/B and VC to	the corresponding	
Vb	Input	Dutput buffer adjustment input This signal allows the capacity of the LCD drive output buffer to be varied depending on the voltage applied to it. The lower the applied voltage, the greater the drive capacity.					
VA VB VC	Input	Analog signal input These pins accept LCD drive output		nput the anal	og signals tha	t are output to the	

PIN NAME	1/0	FUNCTION
QA1 to 80		LCD drive output
QB1 to 80	Output	These pins output one of the analog signal inputs (VA, VB or VC) after it
QC1 to 80		has been sampled and held by the sample-and-hold circuit.
V _{SEG}		Power supply for the device's high-voltage block
V_{DD}		Power supply for the device's logic block
V _{SS}		Common GND for the device

DEVICE OPERATION (see timing diagram)

(1) Analog signal sampling

Data transfer begins with the assertion of DI/O (when U/D = high) or DO/I (when U/D = low). The table below shows the relation between the shift clocks and the analog signals.

U/D	CPH1	CPH2	СРН3
Н	QA1 to 80	QB1 to 80	QC1 to 80
L	QC80 to 1	QB80 to 1	QA80 to 1

<When U/D = high>

- A high on DI/O is latched into the internal logic synchronously with the rising edge of CPH1, and the analog signal to be output to QA1 is sampled at the next rising edge of CPH1. In this way, all analog signals are sampled sequentially at each rising edge of CPH2, CPH3, CPH1, CPH2, CPH3 and so on, as the analog signals are output to QB1, QC1, QA2, QB2, QC2 and so on.
- After the device finishes sampling the data for QC80, it automatically enters standby state. Unless DI/O is asserted again, no data is sampled, irrespective of whether CPH1 to CPH3 are input to the device.

<When U/D = low>

- A high on DO/I is latched into the internal logic synchronously with the rising edge of CPH1, and the analog signal to be output to QC80 is sampled at the next rising edge of CPH1. In this way, all analog signals are sampled sequentially at each rising edge of CPH2, CPH3, CPH1, CPH2, CPH3 and so on and the analog signals are output to QB80, QA80, QC79, QB79, QA79 and so on.
- After the device finishes sampling the data for QA1, it automatically enters standby state. Unless DO/I is asserted again, no data is sampled, irrespective of whether CPH1 to CPH3 are input to the device.

Analog signal inputs VA, VB and VC are fed into the sample-and-hold circuits before they are forwarded to the LCD drive outputs: QA1-80, QB1-80 and QC1-80. Which analog input is sampled and held by which LCD drive output is determined by the Q1H/Q2H select signal as shown below.

ANALOG SIGNAL	INPUT SELECT PIN	ANALOG SIGNAL	LCD DRIVE OUTPUT			
Q1H	Q2H	INPUT	U/D = high	U/D = low		
		VA	QC1 to 80	QA1 to 80		
0	0	VB	QB1 to 80	QB1 to 80		
		VC	QA1 to 80	QC1 to 80		
		VA	QA1 to 80	QB1 to 80		
0	1	VB	QC1 to 80	QC1 to 80		
		VC	QB1 to 80	QA1 to 80		
		VA	QB1 to 80	QC1 to 80		
1	0/1	VB	QA1 to 80	QA1 to 80		
		VC	QC1 to 80	QB1 to 80		

(2) LCD drive output

When OE is driven high, the sampled-and-held data is fed to the LCD drive output pins (QA1 through QC80).

The LCD drive output is enabled when OE is high; it is put in the Hi-Z state when OE is low.

OE should be kept low while the device is sampling data.

The drive capabilities of the LCD drive output pins are controlled by the output buffer adjustment input (Vb). The drive capability is at a minimum when $Vb = V_{SEG}$ and decrease as the Vb voltage is raised, hence the drive capability can be set to the desired level.

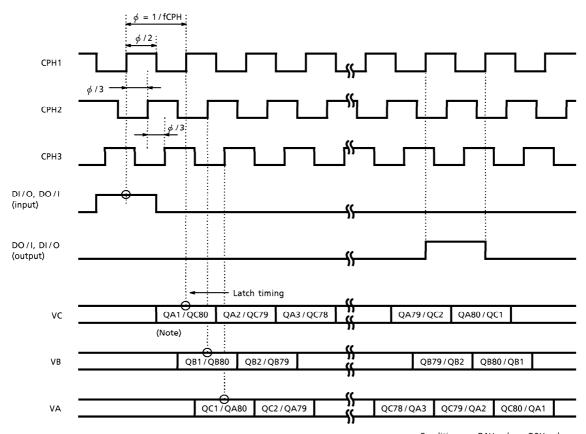
(3) Vertical shift data output

The output DO/I (when U/D = high) or DI/O (when U/D = low) is driven high for one clock period synchronously with the rising edge of CPH1 one clock period before the data to be output to QA80 or QC1 is latched into the shift register (see timing diagram).

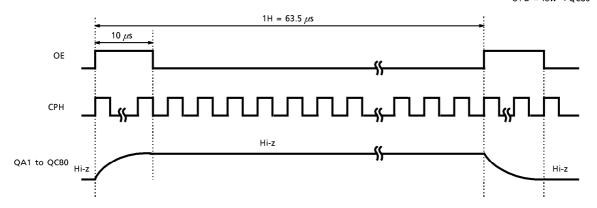
(4) Expanding LCD drive output

When using two or more of these devices to drive a large screen, connect the vertical shift data output from the first stage of the LCD driver directly to the vertical shift data input at the next stage. In this way, the device's LCD drive output pin can easily be expanded as necessary.

TIMING DIAGRAM



Conditions Q1H = low, Q2H = low (Note) : QA1/QC80 : U/D = high \rightarrow QA1 U/D = low \rightarrow QC80



ABSOLUTE MAXIMUM RATINGS $(V_{SS} = 0 V)$

PARAMETER	SYMBOL	RATING	UNIT	RELEVANT PIN
Supply Voltage (1)	V _{SEG}	-0.3 to 18	V	
Supply Voltage (2)	V _{DD}	-0.3 to 7.0	V	
Input Voltage	V _{IN}	-0.3 to V _{DD} + 0.3	V	(Note 1)
Storage Temperature	T _{stg}	– 55 to 125	°C	
Analog Input Voltage	VVIDEO	-0.3 to V _{SEG} + 0.3	V	(Note 2)

RECOMMENDED OPERATING CONDITIONS ($V_{SS} = 0 V$)

PARAMETER	SYMBOL	RATING	UNIT	RELEVANT PIN
Supply Voltage (1)	V_{SEG}	V _{DD} to 15	V	
Supply Voltage (2)	V_{DD}	4.5 to 5.5	V	
Operating Temperature	T _{OP}	-20 to 75	°C	
Operating Frequency	fCPH	0.5 to 6.0	MHz	
Output Load Capacitance	C_L	0 to 200	pF	
Analog Input Voltage	VVIDEO	1.0 to V _{SEG} - 2.0	V	(Note 2)

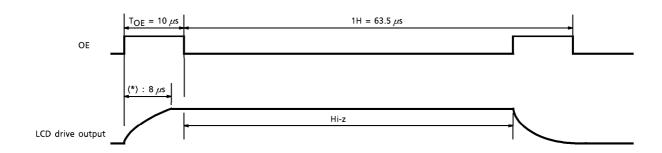
(Note 1) : All input pins except the analog signal input pins (VA, VB, VC and Vb) (Note 2) : Analog signal input pins (VA, VB, VC and Vb)

ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS (Referenced to $V_{DD}=4.5$ to $5.5\,V$, $V_{SEG}=13\,V$, $V_{SS}=0\,V$, $T_{a}=-20$ to $75^{\circ}C$ unless otherwise noted

PARAMETER		SYMBOL	TEST CIR- CUIT	TEST CONDITIONS	MIN	TYP.	MAX	UNIT	RELEVANT PIN
Input	Low Level	V _{IL}	_		0		0.2 × V _{DD}	v	Logic input
Voltage	High Level	VIH			0.8 × V _{DD}		V _{DD}	V	Logic input
Output	Low Level	V _{OL}	ı	I _{OL} = 40 μA	V _{SS}		V _{SS} + 0.3	- v	DI/O, DO/I
Voltage	High Level	Vон		l _{OH} = -40 μA	V _{DD} - 0.3		V _{DD}		
Output Offs	Output Offset Voltage		_		- 50.0		50.0	mV	QA1 to QC80
Output Curr	ent	lOL		(Note 3)		0.2		mA	QA1 to QC80
Output Leakage Current		ID _{LEAK}		OE = Low	- 1.0		1.0	μΑ	
Input Current		IN	l		- 1.0		1.0	μΑ	Logic input
Current Consumption (1)		lDD		(Note 4)				mA	
Current Con (2)	sumption	ISEG		(Note 4)				mA	

(Note 3) : Vb = 11 V, V_{VIDEO} = 11 V (Note 4) : f_{CPH} = 3 MHz, 1H = 63.5 μ s, TOE = 10 μ s, V_{VIDEO} = amplitude of 1 to 11 V, load capacitance = 100 pF (all output pins)

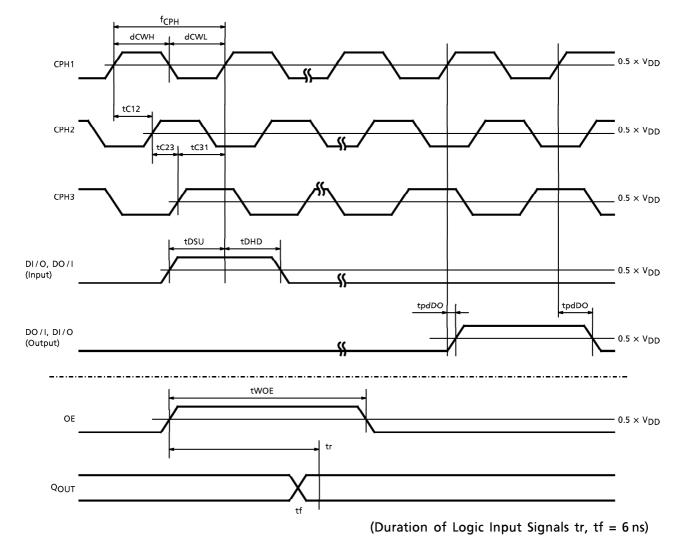


(*) : This interval can be varied by adjusting Vb.

AC CHARACTERISTICS (Referenced to V_{DD} = 4.5 to 5.5 V, V_{SEG} = 13 V, V_{SS} = 0 V, Ta = -20 to 75°C unless otherwise noted

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	MAX	UNIT
Operating Frequency	f _{CPH} (1/tCPH)		0.5	6	MHz
Clock to Clock Delay Time	tC12, tC23, tC31		40	tCPH/2	ns
CPH Pulse Duty Cycle	dCWH/dCWL		40	60	%
Data Set-up Time	tDSU		20		ns
Data Hold Time	tDHD		60		ns
Output Delay Time	tpdDO	CL = 30 pF		60	ns
OE Pulse Width	tWOE		5	20	μ s

(Note): The Qout rise and fall times (tr, tf) can be varied by changing Vb.



(*): Use OE with a period at 63.5 ns intervals.